

**METHOD FOR MANUFACTURING AN INTERCONNECTED CIRCUIT
BOARD ASSEMBLY AND SYSTEM**

Abstract of the Disclosure

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An electrical assembly (200, Figure 2) is formed from two, interconnected circuit boards (202, 204). Conductive spacers (240) and a conductive material (260) are placed between complementary bond pads (218, 232) on the circuit boards. The conductive spacers are formed from a material that maintains its mechanical 10 integrity during the process of attaching the circuit boards. The conductive material is a solder or conductive adhesive used to mechanically attach the circuit boards. In addition, an insulating material (270) is inserted into an interface region (250) between the circuit boards. The insulating material provides additional mechanical connection between the circuit boards. In one embodiment, one circuit board (202) 15 includes a glass panel that holds an array of organic light emitting diodes (OLEDs), and the other circuit board (204) is a ceramic circuit board. Together, the interconnected circuit board assembly (200) forms a portion of a flat panel display (1102, Figure 11).

"Express Mail" mailing label number: EV3325683090US

Date of Deposit: July 28, 2003

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